

X-CON BRAND

CONDUCTIVE POLYMER ALUMINUM SOLID CAPACITORS

PRODUCT SPECIFICATION 規格書

CUSTOMER: (客户): DATE: (日期): 2015-10-22

CATEGORY (品名)	:	CONDUCTIVE POLYMER ALUMINUM
		SOLID CAPACITORS
DESCRIPTION (型号)	:	ULR 6.3V330 μ F (φ6.3x8)
VERSION (版本)		01
VERSION (h)242)	·	01
Customer P/N	:	/
SUPPLIER	:	/

SUPPL	IER	CUST	OMER
PREPARED (拟定)	CHECKED (审核)	APPROVAL (批准)	SIGNATURE (签名)
郭梦玉	王国华		

SAMXON ELECTRONIC COMPONENTS LIMITED



		SPECIFICAT	TION		ALTERN	ATION HIS	TORY
		ULR SERI		ECORDS			
Rev.	Date	Mark	Page	Contents	Purpose	Drafter	Approver

Issued-date: 2015-10-22	Name	Specification Sheet – ULR				
Version	Version 01 Page 1					
	STA	ANDARD MANUAL				

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<u> </u>		ULR					
Rev.	Date	Mark	Page	Contents	Purpose	Design	Cnfm

Issued-date: 2015-10-22	Name	Specification Sheet – ULR				
Version	Version 01 Page 2					
	STA	ANDARD MANUAL				

SAMXON ELECTRONIC COMPONENTS LIMITED

1.Application32.Part Number System33.Construction44.Characteristics5~14.1Rated voltage & Surge voltage5~14.2Capacitance (Tolerance)44.3Leakage current44.4Tangent of loss angle54.5ESR64.6Temperature characteristic74.7Load life test44.8Surge test44.10Maximum permissible ripple current44.13Resistance to vibration44.14Solderability44.15Resistance to soldering heat55.Product Dimensions, Impedance & Maximum Permissible Ripple Current17.1Circuit design127.2Voltage77.3Sudden charge and discharge restricted7-47.4Ripple current7-57.5Leakage current7-67.6Precautions for using capacitors15	2. Part Number System 3 3. Construction 4 4. Characteristics 5~11 4. Characteristics 5~11 4. Rated voltage & Surge voltage 5~11 4. Capacitance (Tolerance) 5~11 4.3 Leakage current 5~11 4.4 Tangent of loss angle 5 4.5 ESR 5 4.6 Temperature characteristic 7 4.7 Load life test 4 4.8 Surge test 4 4.9 Damp heat test 4 4.10 Maximum permissible ripple current 4 4.11 Resistance to vibration 4 4.12 Lead strength 12 4.13 Resistance to soldering heat 12 5. Product Marking 12 6. Product Marking 12 7. Application Guideline 14~15 7.1 Circuit design 12 7.2 Voltage 13 7.3 Sudden charge and discharge r	C O N T E N T S	
2.Part Number System33.Construction44.Characteristics5~14.Rated voltage & Surge voltage5~14.Rated voltage & Surge voltage5~14.Tangent of loss angle54.Temperature characteristic74.Tangent of loss angle64.Surge test74.Ange of temperature74.12 Lead strength74.13 Resistance to vibration74.14 Solderability74.15 Resistance to soldering heat75.Product Dimensions, Impedance & Maximum Permissible Ripple Current17.1 Circuit design127.2 Voltage77.3 Sudden charge and discharge restricted77.4 Ripple current77.5 Leakage current77.6 Failure rate77.7 Capacitor insulation77.8 Precautions for using capacitors15	2.Part Number System33.Construction44.Characteristics5~114.Rated voltage & Surge voltage5~114.1Rated voltage & Surge voltage5~114.2Capacitance (Tolerance)44.3Leakage current44.4Tangent of loss angle44.5ESR44.6Temperature characteristic44.7Load life test44.8Surge test44.9Damp heat test44.10Maximum permissible ripple current44.11Rapid change of temperature44.12Lead strength44.13Resistance to vibration44.14Solderability44.15Resistance to soldering heat125.Product Dimensions, Impedance & Maximum Permissible Ripple Current137.Application Guideline14~157.1Circuit design127.2Voltage77.3Sudden charge and discharge restricted77.4Ripple current77.5Leakage current77.6Precautions for using capacitors15		Sheet
2.Part Number System33.Construction44.Characteristics5~14.Rated voltage & Surge voltage5~14.Rated voltage & Surge voltage5~14.Tangent of loss angle54.Temperature characteristic74.Tangent of loss angle64.Surge test74.Ange of temperature74.12 Lead strength74.13 Resistance to vibration74.14 Solderability74.15 Resistance to soldering heat75.Product Dimensions, Impedance & Maximum Permissible Ripple Current17.1 Circuit design127.2 Voltage77.3 Sudden charge and discharge restricted77.4 Ripple current77.5 Leakage current77.6 Failure rate77.7 Capacitor insulation77.8 Precautions for using capacitors15	2.Part Number System33.Construction44.Characteristics5~114.Rated voltage & Surge voltage5~114.1Rated voltage & Surge voltage5~114.2Capacitance (Tolerance)44.3Leakage current44.4Tangent of loss angle44.5ESR44.6Temperature characteristic44.7Load life test44.8Surge test44.9Damp heat test44.10Maximum permissible ripple current44.11Rapid change of temperature44.12Lead strength44.13Resistance to vibration44.14Solderability44.15Resistance to soldering heat125.Product Dimensions, Impedance & Maximum Permissible Ripple Current137.Application Guideline14~157.1Circuit design127.2Voltage77.3Sudden charge and discharge restricted77.4Ripple current77.5Leakage current77.6Precautions for using capacitors15	1. Application	3
3.Construction44.Characteristics5~14.Rated voltage & Surge voltage5~14.1Rated voltage & Surge voltage5~14.2Capacitance (Tolerance)44.3Leakage current44.4Tangent of loss angle54.5ESR64.6Temperature characteristic74.7Load life test44.8Surge test44.9Damp heat test44.10Maximum permissible ripple current44.11Rapid change of temperature44.12Lead strength44.13Resistance to vibration44.14Solderability126.Product Dimensions, Impedance & Maximum Permissible Ripple Current17.Application Guideline14~17.2Voltage737.3Sudden charge and discharge restricted47.4Ripple current757.5Leakage current767.6Failure rate777.7Capacitor insulation787.8Mounting Precautions15	 Construction 4 Characteristics 5~11 Rated voltage & Surge voltage Capacitance (Tolerance) Leakage current Tangent of loss angle ESR Temperature characteristic Toal life test Surge test Surge test Damp heat test Capacitance to vibration Resistance to vibration Solderability Sesistance to soldering heat Product Dimensions, Impedance & Maximum Permissible Ripple Current Circuit design Voltage Sudden charge and discharge restricted A Ripple current Seakage current <li< td=""><td></td><td>3</td></li<>		3
 4. Characteristics 5~1 4.1 Rated voltage & Surge voltage 4.2 Capacitance (Tolerance) 4.3 Leakage current 4.4 Tangent of loss angle 4.5 ESR 4.6 Temperature characteristic 4.7 Load life test 4.8 Surge test 4.9 Damp heat test 4.10 Maximum permissible ripple current 4.11 Rapid change of temperature 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 1.7 Application Guideline 7.4 Voltage 7.3 Sudden charge and discharge restricted 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 	 4. Characteristics 5~11 4.1 Rated voltage & Surge voltage 4.2 Capacitance (Tolerance) 4.3 Leakage current 4.4 Tangent of loss angle 4.5 ESR 4.6 Temperature characteristic 4.7 Load life test 4.8 Surge test 4.9 Damp heat test 4.10 Maximum permissible ripple current 4.11 Rapid change of temperature 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Dimensions, Impedance & Maximum Permissible Ripple Current 13 Reprised end discharge restricted 7.4 Poldage 7.2 Voltage 7.3 Sudden charge and discharge restricted 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 3. Mounting Precautions 		
 4.1 Rated voltage & Surge voltage 4.2 Capacitance (Tolerance) 4.3 Leakage current 4.4 Tangent of loss angle 4.5 ESR 4.6 Temperature characteristic 4.7 Load life test 4.8 Surge test 4.9 Damp heat test 4.10 Maximum permissible ripple current 4.11 Rapid change of temperature 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 1 Application Guideline 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 	 4.1 Rated voltage & Surge voltage 4.2 Capacitance (Tolerance) 4.3 Leakage current 4.4 Tangent of loss angle 4.5 ESR 4.6 Temperature characteristic 4.7 Load life test 4.8 Surge test 4.9 Damp heat test 4.10 Maximum permissible ripple current 4.11 Rapid change of temperature 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 13 Rapication Guideline 7.4 Coltage 7.3 Sudden charge and discharge restricted 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 		
 4.2 Capacitance (Tolerance) 4.3 Leakage current 4.4 Tangent of loss angle 4.5 ESR 4.6 Temperature characteristic 4.7 Load life test 4.8 Surge test 4.9 Damp heat test 4.10 Maximum permissible ripple current 4.11 Rapid change of temperature 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 1 7.1 Circuit design 7.2 Voltage 7.3 Sudden charge and discharge restricted 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 	 4.2 Capacitance (Tolerance) 4.3 Leakage current 4.4 Tangent of loss angle 4.5 ESR 4.6 Temperature characteristic 4.7 Load life test 4.8 Surge test 4.9 Damp heat test 4.10 Maximum permissible ripple current 4.11 Rapid change of temperature 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Dimensions, Impedance & Maximum Permissible Ripple Current 13 Rogitation Guideline 5. Product Dimensions, Impedance & Maximum Permissible Ripple Current 6. Product Dimensions, Impedance Testricted 7.4 Ripple current 7.5 Leakage current 7.6 Evaluer rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 		0 11
 4.3 Leakage current 4.4 Tangent of loss angle 4.5 ESR 4.6 Temperature characteristic 4.7 Load life test 4.8 Surge test 4.9 Damp heat test 4.10 Maximum permissible ripple current 4.11 Rapid change of temperature 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 1 7. Application Guideline 7.4 Solden charge and discharge restricted 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 	 4.3 Leakage current 4.4 Tangent of loss angle 4.5 ESR 4.6 Temperature characteristic 4.7 Load life test 4.8 Surge test 4.9 Damp heat test 4.10 Maximum permissible ripple current 4.11 Rapid change of temperature 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Dimensions, Impedance & Maximum Permissible Ripple Current 13 Robustion Guideline 7. Application Guideline 7. Application Guideline 7.3 Sudden charge and discharge restricted 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 		
 4.4 Tangent of loss angle 4.5 ESR 4.6 Temperature characteristic 4.7 Load life test 4.8 Surge test 4.8 Surge test 4.9 Damp heat test 4.10 Maximum permissible ripple current 4.11 Rapid change of temperature 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 1 7.4 Optication Guideline 7.4 Noplication Guideline 7.4 Nipple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 	 4.4 Tangent of loss angle 4.5 ESR 4.6 Temperature characteristic 4.7 Load life test 4.8 Surge test 4.9 Damp heat test 4.10 Maximum permissible ripple current 4.11 Rapid change of temperature 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Dimensions, Impedance & Maximum Permissible Ripple Current 13 7.Application Guideline 7.2 Voltage 7.3 Sudden charge and discharge restricted 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 		
 4.5 ESR 4.6 Temperature characteristic 4.7 Load life test 4.8 Surge test 4.9 Damp heat test 4.10 Maximum permissible ripple current 4.11 Rapid change of temperature 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 11 Application Guideline 7.4 North Circuit design 7.2 Voltage 7.3 Sudden charge and discharge restricted 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 	 4.5 ESR 4.6 Temperature characteristic 4.7 Load life test 4.8 Surge test 4.9 Damp heat test 4.10 Maximum permissible ripple current 4.11 Rapid change of temperature 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 13 7.Application Guideline 7.4 Voltage 7.3 Sudden charge and discharge restricted 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 3. Mounting Precautions 		
 4.7 Load life test 4.8 Surge test 4.9 Damp heat test 4.10 Maximum permissible ripple current 4.11 Rapid change of temperature 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 1 7. Application Guideline 7.4 Nipple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 	 4.7 Load life test 4.8 Surge test 4.9 Damp heat test 4.10 Maximum permissible ripple current 4.11 Rapid change of temperature 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 13 7.Application Guideline 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 		
 4.7 Load life test 4.8 Surge test 4.9 Damp heat test 4.10 Maximum permissible ripple current 4.11 Rapid change of temperature 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 1 7. Application Guideline 7.4 Nipple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 	 4.7 Load life test 4.8 Surge test 4.9 Damp heat test 4.10 Maximum permissible ripple current 4.11 Rapid change of temperature 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 7. Application Guideline 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 		
 4.9 Damp heat test 4.10 Maximum permissible ripple current 4.11 Rapid change of temperature 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 1 7.4 Application Guideline 7.2 Voltage 7.3 Sudden charge and discharge restricted 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 	 4.9 Damp heat test 4.10 Maximum permissible ripple current 4.11 Rapid change of temperature 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 7. Application Guideline 7.4 Ripple current 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 		
 4.10 Maximum permissible ripple current 4.11 Rapid change of temperature 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 1 7. Application Guideline 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 	 4.10 Maximum permissible ripple current 4.11 Rapid change of temperature 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 7. Application Guideline 7.4 Circuit design 7.2 Voltage 7.3 Sudden charge and discharge restricted 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 	4.8 Surge test	
 4.11 Rapid change of temperature 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 1 7. Application Guideline 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 	 4.11 Rapid change of temperature 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 13 7.Application Guideline 7.4 Circuit design 7.2 Voltage 7.3 Sudden charge and discharge restricted 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 	4.9 Damp heat test	
 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 7. Application Guideline 7.4 Circuit design 7.2 Voltage 7.3 Sudden charge and discharge restricted 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 	 4.12 Lead strength 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 13 7.Application Guideline 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 15 		
 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 7. Application Guideline 7.4 Circuit design 7.2 Voltage 7.3 Sudden charge and discharge restricted 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 	 4.13 Resistance to vibration 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 7. Application Guideline 7.4 Circuit design 7.2 Voltage 7.3 Sudden charge and discharge restricted 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 		
 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 7. Application Guideline 7.4 Circuit design 7.2 Voltage 7.3 Sudden charge and discharge restricted 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 15 	 4.14 Solderability 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 13 7. Application Guideline 7.4 Circuit design 7.2 Voltage 7.3 Sudden charge and discharge restricted 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 		
 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 7. Application Guideline 7.1 Circuit design 7.2 Voltage 7.3 Sudden charge and discharge restricted 7.4 Ripple current 7.5 Leakage current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 15 	 4.15 Resistance to soldering heat 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 7. Application Guideline 7.1 Circuit design 7.2 Voltage 7.3 Sudden charge and discharge restricted 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 15 		
 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 7. Application Guideline 7. Application Guideline 7. Circuit design 7. Voltage 7. Sudden charge and discharge restricted 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 12 	 5. Product Marking 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 7. Application Guideline 7.1 Circuit design 7.2 Voltage 7.3 Sudden charge and discharge restricted 7.4 Ripple current 7.5 Leakage current 7.6 Failure rate 7.7 Capacitor insulation 7.8 Precautions for using capacitors 8. Mounting Precautions 12 13 14~15 14~15 15 		
 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 1 7. Application Guideline 14~1 7-1 Circuit design 7-2 Voltage 7-3 Sudden charge and discharge restricted 7-4 Ripple current 7-5 Leakage current 7-6 Failure rate 7-7 Capacitor insulation 7-8 Precautions for using capacitors 8. Mounting Precautions 15 	 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current 13 7. Application Guideline 14~15 7-1 Circuit design 7-2 Voltage 7-3 Sudden charge and discharge restricted 7-4 Ripple current 7-5 Leakage current 7-6 Failure rate 7-7 Capacitor insulation 7-8 Precautions for using capacitors 8. Mounting Precautions 15 	-	10
7. Application Guideline14~17-1 Circuit design14~17-2 Voltage14~17-3 Sudden charge and discharge restricted14~17-4 Ripple current14~17-5 Leakage current157-6 Failure rate157-7 Capacitor insulation15	7. Application Guideline 14~15 7-1 Circuit design 14~15 7-2 Voltage 14~15 7-3 Sudden charge and discharge restricted 14~15 7-4 Ripple current 14~15 7-5 Leakage current 14~15 7-6 Failure rate 14~15 7-7 Capacitor insulation 15 8. Mounting Precautions 15	•	
 7-1 Circuit design 7-2 Voltage 7-3 Sudden charge and discharge restricted 7-4 Ripple current 7-5 Leakage current 7-6 Failure rate 7-7 Capacitor insulation 7-8 Precautions for using capacitors 8. Mounting Precautions 15 	 7-1 Circuit design 7-2 Voltage 7-3 Sudden charge and discharge restricted 7-4 Ripple current 7-5 Leakage current 7-6 Failure rate 7-7 Capacitor insulation 7-8 Precautions for using capacitors 8. Mounting Precautions 15 		
 7-2 Voltage 7-3 Sudden charge and discharge restricted 7-4 Ripple current 7-5 Leakage current 7-6 Failure rate 7-7 Capacitor insulation 7-8 Precautions for using capacitors 8. Mounting Precautions 15 	 7-2 Voltage 7-3 Sudden charge and discharge restricted 7-4 Ripple current 7-5 Leakage current 7-6 Failure rate 7-7 Capacitor insulation 7-8 Precautions for using capacitors 8. Mounting Precautions 15 		14~15
 7-3 Sudden charge and discharge restricted 7-4 Ripple current 7-5 Leakage current 7-6 Failure rate 7-7 Capacitor insulation 7-8 Precautions for using capacitors 8. Mounting Precautions 15 	 7-3 Sudden charge and discharge restricted 7-4 Ripple current 7-5 Leakage current 7-6 Failure rate 7-7 Capacitor insulation 7-8 Precautions for using capacitors 8. Mounting Precautions 15 		
 7-4 Ripple current 7-5 Leakage current 7-6 Failure rate 7-7 Capacitor insulation 7-8 Precautions for using capacitors 8. Mounting Precautions 15 	 7-4 Ripple current 7-5 Leakage current 7-6 Failure rate 7-7 Capacitor insulation 7-8 Precautions for using capacitors 8. Mounting Precautions 15 	-	
 7-5 Leakage current 7-6 Failure rate 7-7 Capacitor insulation 7-8 Precautions for using capacitors 8. Mounting Precautions 15 	 7-5 Leakage current 7-6 Failure rate 7-7 Capacitor insulation 7-8 Precautions for using capacitors 8. Mounting Precautions 15 		
 7-6 Failure rate 7-7 Capacitor insulation 7-8 Precautions for using capacitors 8. Mounting Precautions 15 	 7-6 Failure rate 7-7 Capacitor insulation 7-8 Precautions for using capacitors 8. Mounting Precautions 15 	••	
7-7 Capacitor insulation7-8 Precautions for using capacitors8. Mounting Precautions15	 7-7 Capacitor insulation 7-8 Precautions for using capacitors 8. Mounting Precautions 15 		
7-8 Precautions for using capacitors8. Mounting Precautions15	7-8 Precautions for using capacitors 15 8. Mounting Precautions 15		
8. Mounting Precautions 15	3. Mounting Precautions 15		
0	0		1.5
	9 . List of "Environment-related Substances to be Controlled ('Controlled Substances')"16	-	
9. List of "Environment-related Substances to be Controlled ("Controlled Substances")"		9. List of "Environment-related Substances to be Controlled ('Controlled Substa	inces')" 16

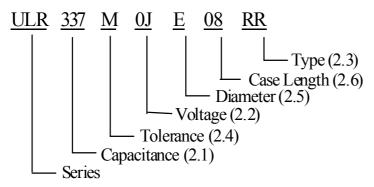
Issued-date: 2015-10-22	Name	Specification Sheet – ULR				
Version	Version 01 Page 3					
	STA	ANDARD MANUAL				

SAMXON ELECTRONIC	Conductive Polymer Aluminum Solid Capacitors	X-CON
COMPONENTS LIMITED	ULR Series	

1. Application

This specification applies to conductive polymer aluminum solid capacitors used in electronic equipment.

2. Part Number System



2.1 <u>Capacitance code</u>

Code	337
Capacitance (µF)	330

2.2 <u>Rated voltage code</u>

Code	0J
Voltage (W.V.)	6.3

2.3 <u>Type</u>

Code	RR
Туре	Bulk

2.4 <u>Capacitance tolerance</u> "M" stands for $-20\% \sim +20\%$

2.5 <u>Diameter</u>

Code	Е
Diameter	6.3

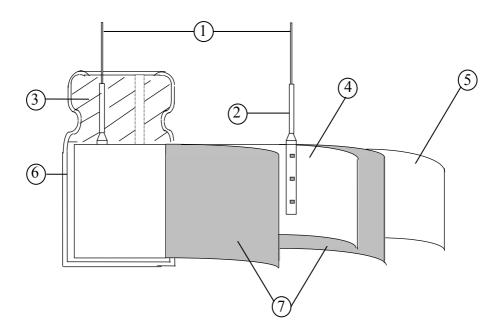
2.6 <u>Case length</u> 08=8mm

Issued-date: 2015-10-22	Name	Specification Sheet – ULR		
Version	01		Page	4
	STA	ANDARD MANUAL		

SAMXON ELECTRONIC	Conductive Polymer Aluminum Solid Capacitors	X-CON
COMPONENTS LIMITED	ULR Series	

3.Construction

Single ended type to be produced to fix the terminals to anode and cathode foil, and wind together with paper, and then wound element to be formed and carbonized, impregnated with polymer and polymerized, then will be enclosed in an aluminum case. Finally sealed up tightly with end seal rubber.



No	Component	Material
1	Lead Line	Tinned Copper Line or CP Line(Pb Free)
2	Terminal	Aluminum
3	Sealing Material	Rubber
4	Al-Foil (+)	Aluminum
5	Al-Foil (-)	Aluminum
6	Case	Aluminum
7	Electrolyte paper	Manila Hemp

Issued-date: 2015-10-22	Name	Specification Sheet – ULR		
Version	01		Page	5
	STA	ANDARD MANUAL		

4. Characteristics

Standard atmospheric conditions

Unless otherwise specified, the standard range of atmospheric conditions for making measurements and tests is as follows:

Ambient temperature:15°C to 35°CRelative humidity:45% to75%Air Pressure:86kPa to 106kPa

If there is any doubt about the results, measurement shall be made within the following conditions: Ambient temperature: $20^{\circ}C \pm 2^{\circ}C$ Relative humidity : 60% to 70%Air Pressure : 86kPa to 106kPa

Operating temperature range

The ambient temperature range at which the capacitor can be operated continuously at rated voltage is -55°C to 105°C.

Issued-date: 2015-10-22	Name	Specification Sheet – ULR		
Version	01		Page	6
	STA	ANDARD MANUAL		

SAMXON ELECTRONIC
COMPONENTS LIMITED
COMI ONEMIS LIMITED

	ITEM	PERFORMANCE
4.1	Rated voltage (WV) Surge voltage (SV)	WV (V.DC) 6.3 SV (V.DC) 7.2
4.2	Nominal capacitance (Tolerance)	<condition>Measuring Frequency: 120Hz\pm12HzMeasuring Voltage: Not more than 0.5VrmsMeasuring Temperature: $20\pm 2^{\circ}C$<criteria>Shall be within the specified capacitance tolerance.</criteria></condition>
4.3	Leakage current	<condition></condition> After DC Voltage is applied to capacitors through the series protective resistor (1k $\Omega \pm 10 \Omega$) so that terminal voltage may reach the rated voltage .The leakage current when measured after 2 minutes shall not exceed the values of the following equation. In case leakage current value exceed the value shown in Table 3, remeasure after voltage treatment that applies the rated voltage shown in 4.1 for 120minutes at 105 °C <criteria></criteria> See Table 3
4.4	tan δ	<condition>See 4.2, for measuring frequency, voltage and temperature.<criteria>Working voltage (v)$6.3$$\tan \delta$ (max.)0.10</criteria></condition>
4.5	ESR	Condition> Measuring frequency : 100kHz to 300kHz; Measuring temperature:20±2°C Measuring point : 2mm max from the surface of a sealing resin on the lead wire. Criteria> (20°C)Less than the initial limit(See Table 3).

Issued-date: 2015-10-22	Name	Specification Sheet – ULR		
Version	01		Page	7
	STA	ANDARD MANUAL		

SAMXON ELECTRONIC
COMPONENTS LIMITED

		STEP	Temperature(°C)	Item	Characteristics		
				Measure: Capacitance			
				1	20 ± 2	tanδ Impedance	
		2	-55+3	Z-55°C / 20°C	≤1.25		
	Temperature	3	Keep at 15 to 35°C f	or			
4.6	characteristic	4	105 ± 2	Z105°C / 20°C	≤1.25		
	enaracteristic			∆ C/C 20°C	Within \pm 5% of step1		
		5	20 ± 2	tanð	Less than or equal to the value of item 4.4		
		The Ca	ge for 2000 +48/0 hours teria>	Solution the result should meet $\pm 2 ^{\circ}$			
		Item					
		Capa		Within $\pm 20\%$ of initial capacitance			
		tan δ		ess than or equal to 1.5 em 4.4	times of the value of		
	Load	ESR		ess than or equal to 1.5 em 4.5	times of the value of		
4.7	life	Leak	tage current L	ess than or equal to the v	alue of item 4.3		
	test	Appe	earance N	otable changes shall not	be found.		
4.7		Capa tan δ ESR Leak	acitance Change W L itu tage current L	ess than or equal to 1.5 em 4.4 ess than or equal to 1.5 em 4.5 ess than or equal to the v	times of the valu times of the valu alue of item 4.3		

Issued-date: 2015-10-22	Name	Specification Sheet – ULR				
Version	01		Page	8		
STANDARD MANUAL						

SAMXON ELECTRONIC COMPONENTS LIMITED

Conductive Polymer Aluminum Solid Capacitors ULR Series



4.8	Surge test		e 15~35℃.
		Leakage current Attention: This test sin hypothesizing that over v	Less than or equal to the value of item 4.3 nulates over voltage at abnormal situation, and not be oltage is always applied.
4.9	Damp heat test	-	exposed for 1000 ± 48 hours in an atmosphere of 90~95%RH at istic change shall meet the following requirement. Performance Within $\pm 20\%$ of initial capacitance Less than or equal to 1.5 times of the value of item 4.4 Less than or equal to 1.5 times of the value of item 4.5 Less than or equal to the value of item 4.3 Notable changes shall not be found.

Issued-date: 2015-10-22	Name	Specification Sheet – ULR				
Version	01		Page	9		
STANDARD MANUAL						

SAMXON ELECTRONIC	Conductive Polymer Aluminum Solid Capacitors	X-CON
COMPONENTS LIMITED	ULR Series	

4.10	Maximum permissible (ripple current)	<condition> The maximum per At 100kHz and car Table 3 The combined valu rated voltage and s Frequency Multipl Frequency Coefficient</condition>	n be applied at ue of D.C volta shall not revers	maximum oper ge and the peak	rating temperatur	e see
4.11	Rapid change of temperature	Applied voltage: wi Cycle number: 5 cy Test diagram: Fig.1 Performance: The c Item Capacitance chang tan δ Leakage current	apacitors shall Performan ge Within ± Less than	meet the follow nce 10% of initial or equal to valu or equal to the	Room $30 \pm 3 \min$ n or less le ving specification capacitance	

Issued-date: 2015-10-22	Name	Specification Sheet – ULR				
Version	01		Page	10		
STANDARD MANUAL						

SAMXON ELECTRONIC
COMPONENTS LIMITED



		a) Load null strength
		a) Lead pull strength A static load force shall be applied to the terminal in the axial direction and acting
		in a direction away from the body for 10 ± 1 s.
		Lead wire diameter (mm) Load force (N)
		$d \leq 0.5 \qquad 5$
4.12	Lead strength	 b) Lead bending When the capacitor is placed in a vertical position and the weight specified in the table above is applied to one lead and then the capacitor is slowly rotated 90⁰ to a horizontal position and then returned to a vertical position thus completing bends for 2~3seconds. The additional bends are made in the opposite direction
		Lead wire diameter (mm) Load force (N)
		$\frac{1}{d \leq 0.5} \qquad 2.5$
		Performance: The characteristic shall meet the following value after a) or b) test. Item Performance
		ItemPerformanceLeakage currentLess than or equal to the value of item4.3
		Outward Appearance No cutting and slack of lead terminals
		e altra a representation in the calling and black of four terminals
4.13	Resistance to vibration	Frequency: 10 to 55 Hz (1minute interval / 10 \rightarrow 55 \rightarrow 10Hz Amplitude: 0.75mm(Total excursion 1.5mm) Direction :X, Y, Z (3 axes) Duration: 2hours/ axial (Total 6 hours) The capacitors are supported as the following Fig2 $\leqslant 0.3$ mm
		Fig2
		Performance: Capacitance value shall not show drastic change compared to the initial capacitance when the value is measured within 30 minutes. Prior to the completion of exam, Capacitance difference shall be within \pm 5% compared to the initial value the exam.

Issued-date: 2015-10-22	Name	Specification Sheet – ULR				
Version	01		Page	11		
STANDARD MANUAL						

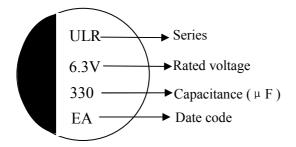
SAMXON ELECTRONIC
COMPONENTS LIMITED

4.14	Solderability	The capacitor shall be tested under the following conditions: Solder : Sn-3Ag-0.5Cu Soldering temperature: 245±3°C Immersing time : 3±0.5s Immersing depth : 1.5~ 2.0mm from the root. Flux : Approx .25% rosin Performance: At least 95% of the dipped portion of the terminal shall be covered with new solder.
4.15	Resistance to soldering	 A) Solder bath method Lead terminals of a capacitor are placed on the heat isolation board with thickness of 1.6±0.5mm. It will dip into the flux of isopropylaehol solution of colophony. Then it will be immersed at the surface of the solder with the following condition: Solder : Sn-3Ag-0.5Cu Soldering temperature : 260 ±5°C Immersing time : 10±1s Heat protector: t=1.6mm glass -epoxy board B) Soldering iron method Bit temperature : 400 ±10°C Application time : 3+1/-0 s Heat protector: t=1.6mm glass -epoxy board For both methods, after the capacitor at thermal stability, the following items shall be measured:
	heat	ItemPerformanceCapacitance ChangeWithin $\pm 5\%$ of initial capacitancetan δ Less than or equal to the value of item 4.4ESRLess than or equal to the value of item 4.5Leakage currentLess than or equal to the value of item 4.3 (after voltage treatment)AppearanceNotable changes shall not be found.

Issued-date: 2015-10-22	Name	Specification Sheet – ULR				
Version	01		Page	12		
STANDARD MANUAL						

5. Product Marking

Marking Sample:



Code Year	Z 2010	A 2011	B 2012	E 2015	-		anufact	ured we	eek: see	Table	2
Table 2 Manufactured year: see Table 1											
Week	1	2	3	4	5	6	7	8	9	10	11
Code	Α	В	С	D	Е	F	G	Н	Ι	J	Κ
Week	12	13	14	15	16	17	18	19	20	21	22
Code	L	М	Ν	0	Р	Q	R	S	Т	U	V
Week	23	24	25	26	27	28	29	30	31	32	33
Code	W	Х	Y	Z	<u>A</u>	B	<u>C</u>	D	E	F	G
Week	34	35	36	37	38	39	40	41	42	43	44
Code	H	I	<u>J</u>	<u>K</u>	L	M	<u>N</u>	<u>0</u>	<u>P</u>	Q	<u>R</u>
Week	45	46	47	48	49	50	51	52			
Code	<u>S</u>	<u>T</u>	U	V	W	<u>X</u>	Y	Z			
									1		

Issued-date: 2015-10-22	Name	Specification Sheet – ULR		
Version	01		Page	13
	STA	ANDARD MANUAL		

SAMXON ELECTRONIC	Conductive Polymer Aluminum Solid Capacitors	X-CON
COMPONENTS LIMITED	ULR Series	

φD	6.3
L	8
F	2.5
φd	0.6

Table 3

Working Voltage (V)	Capacitance (µF)	Dimension (D×L, mm)	Maximum permissible ripple current at 105°C 100kHz (mA rms)	ESR at 20°C100kHz to300kHz (mΩ)	Leakage current (µA) 2min
6.3	330	6.3x8	4500	10	416

Issued-date: 2015-10-22	Name	Specification Sheet – ULR		
Version	01		Page	14
	STA	ANDARD MANUAL		

7.Application Guideline:

X-CON Solid Aluminum Electrolytic Capacitor should be used compliance with the following guidelines

7-1Circuit design

Prohibited Circuits for use

Do not use the capacitors with the following circuits.

1) Time constant circuits

- 2) Coupling circuits
- 3) Circuits which are greatly affected by leakage current
- 4) High impedance voltage retention circuits.
- 7-2. Voltage

1) Over voltage

The application of over-voltage and reverse voltage below can cause increases in leakage current and short circuits. Applied voltage, refers to the voltage value including the peak value of the transitional instantaneous voltage and the peak Value of ripple voltage, not just steady line voltage. Design your circuit so that the peak voltage does not exceed the stipulated voltage.

Over voltage exceeding the rated voltage may not be applied even for an instant as it may cause a short circuit. 2) Applied voltage

① Sum of the DC voltage value and the ripple voltage peak values must not exceed the rated voltage.

(2) When DC voltage is low, negative ripple voltage peak value must not become a reverse voltage that exceeds 10% of The rated voltage.

③ Use the X-CON within 20% of the rated voltage for applications which may cause the reverse voltage during the Transient phenomena when the power is tunid off or the source is switched.

7-3 Sudden charge and discharge restricted

Sudden charge and discharge may result in short circuit's large leakage current. Therefore, a protection circuits are recommended to design in when on of the following condition is expected.

1) The rush current exceeds 10A

2) The rush current exceeds 10 times of allowable ripple current of X-CON.

A protection resistor $(1K \Omega)$ must be inserted to the circuit during the charge and discharge when measuring the leakage Current.

7-4 Ripple current

Use the capacitors within the stipulated permitted ripple current. When excessive ripple current is applied to the capacitor, It causes increases in leakage current and short circuits due to self- heating. Even when using the capacitor under the Permissible ripple current, reverse voltage may occur if the DC bias voltage is low.

7-5 Leakage current

There is a risk of leakage current characteristics increasing even if the following use environments are within the stipulated range However, even if leakage current increases once, it has the characteristic that leakage current becomes small in most cases after voltage is applied due to its self-correction mechanism.

7-6 Failure rate

The main failure mode of X-CON is open mode primarily caused by electrostatic capacity drop at high temperature (i.e.wear out failure), besides random short circuit mode failures primarily caused by over voltage occurs as minor one. The time it takes to reach the failures mode can be extended by using the X-CON with reduced ambient temperature, ripple current and applied voltage.

7-7 Capacitor insulation

1) Insulation in the marking sleeve is not guaranteed. Be aware that the space between the case and the negative electrode Terminal is not insulated and has some resistance.

2) Be sure to completely separate the case, negative lead terminal, and positive lead terminal and PCB patterns with each other.

Issued-date: 2015-10-22	Name	Specification Sheet – ULR				
Version	01		Page	15		
STANDARD MANUAL						

7-8 Precautions for using capacitors

X-CON capacitors should not be used in the following environments.

1) Environments where the capacitor is subject to direct contact with salt water or oil can directly fall on it.

2) Environments where capacitors are exposed to direct sunlight.

3) High temperature (Avoid locating heat generating components around the X-CON and on the underside of the

PCB), or humid environments where condensation can form on the surface of the capacitor.

4) Environments where the capacitor is in contact with chemically active gases.

5) Acid or alkaline environments.

6) Environment subject to high-frequency induction.

7) Environment subject to excessive vibration and shock.

8.Long Term Storage

Store the X-CONs in sealed package bags after delivery per the table below;

X-CON Type	Before unsealing
Radial lead type packed in bags	Must be used within 24~36 months after delivery(unsealed status)
Radial lead type packed in taping method	Must be used within 24~36 months after delivery(unsealed status)

9. Mounting Precautions

Mounting phase	Things to note before mounting	Disposal
	1) Used X-CON capacitors	Not reused
	2) LC-increased X-CON capacitors	Apply them with rated voltage in series with 1K Ω
	after long storage	resistance for 1 hour at the range between 60 and 70° C
	3) X-CON capacitors dropped to the	Not reused
	floor	
Before mounting	4) Precautions on polar, capacitance	Products without remarkable polar, capacitance and rated
Defore mounting	and rated voltage	voltage shouldn't be available
	5) Precautions on the pitch between	The products can be used only when said pitch is matched
	lead terminal and PCB	
	6) Precautions on the stress that lead	The products can be used for production only when lead
	terminal and body of X-CON	terminal and body are not subject stress.
	capacitors enduring in mounting	
	1) Soldering with a soldering iron	Both temperature and duration in mounting should meet
		the requirements of out-going SPEC; no stress should be allowed to occur in mounting; Don't let the tip of the
		soldering iron touch the X-CON itself.
Mounting	2) Flow soldering	X-CON capacitor body should be prohibited to submerge
	2) Thow soldering	in melted solder; both temperature and duration in
		mounting should meet the requirements of out-going
		SPEC; The rosin is not allowed to adhere to any where
		other than lead terminal.
	1) Precautions on mounting status	Do not tilt, bend twists X-CON; Do not allow other matter
		touch X-CON.
	2) Washing the PCB (available	Used immersion or ultrasonic waves to clean for a total of
	cleaning agent 1) high quality	less than 5 minutes and the temperature be less than 60° C;
After mounting	alcohol-based cleaning fluid such as	The conductivity, PH, specific gravity and water cleaning,
	st-100s、750L,750M;2) Detergents	X-CON products should be dried with hot air (less than
	including substitute freon such as	the maximum operating temperature).
	AK-225AES and IPA)	

Issued-date: 2015-10-22	Name	Specification Sheet – ULR		
Version	01		Page	16
	STA	ANDARD MANUAL		

10.It refers to the latest document of "Environment-related Substances standard" (WI-HSPM-QA-072).`

	Substances			
	Cadmium and cadmium compounds			
Heavy metals	Lead and lead compounds			
	Mercury and mercury compounds			
	Hexavalent chromium compounds			
	Polychlorinated biphenyls (PCB)			
Chloinated	Polychlorinated naphthalenes (PCN)			
organic	Polychlorinated terphenyls (PCT)			
compounds	Short-chain chlorinated paraffins(SCCP)			
	Other chlorinated organic compounds			
Draminatad	Polybrominated biphenyls (PBB)			
Brominated	Polybrominated diphenylethers(PBDE) (including			
organic	decabromodiphenyl ether[DecaBDE])			
compounds	Other brominated organic compounds			
Tributyltin comp	oounds(TBT)			
Triphenyltin con	npounds(TPT)			
Asbestos				
Specific azo con	npounds			
Formaldehyde				
Polyvinyl chlorid	de (PVC) and PVC blevds			
Beryllium oxide				
Beryllium copp	er			
Specific phthalat	tes (DEHP,DBP,BBP,DINP,DIDP,DNOP,DNHP)			
Hydrofluorocarb	on (HFC), Perfluorocarbon (PFC)			
Perfluorooctane	sulfonates (PFOS)			
Specific Benzotr	iazole			

Issued-date: 2015-10-22	Name	Specification Sheet – ULR		
Version	01		Page	17
	STA	ANDARD MANUAL		